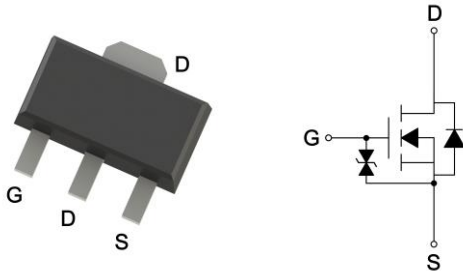


Product Summary

BV_{DSS}	60	V
$R_{DS(ON)}$ typ. @ $V_{GS}=10V, I_D=4A$	28	mΩ
$R_{DS(ON)}$ typ. @ $V_{GS}=4.5V, I_D=3A$	40	
I_D @ $V_{GS}=10V, T_C=25^\circ C$	7	A
I_D @ $V_{GS}=10V, T_A=25^\circ C$	5.5	

SOT-89



Ordering Information

Device	Package	Shipping
MTB025N06KRM3-0-T2-G	SOT-89	1000pcs / Tape & Reel

0: Product rank, zero for no rank products.

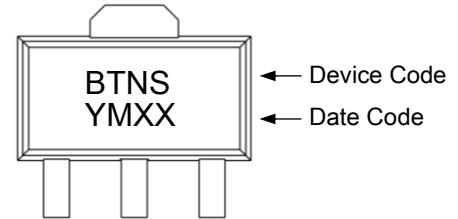
T2: Packing spec, T2 : 1000pcs / tape & reel, 7" reel

G: Environment friendly grade: S for RoHS compliant products, G for RoHS compliant and green compound products.

Features

- Low Gate Charge
- Fast Switching Characteristic
- Pb-free lead plating and halogen-free
- ESD protected gate

Marking



YMXX: Date Code Marking

Y: Year Code, the last digit of Christian year

M: Month Code

A: Jan	B: Feb	C: Mar	D: Apr	E: May	F: Jun
G: Jul	H: Aug	J: Sep	K: Oct	L: Nov	M: Dec

XX: Production Serial Number, 01~99

Absolute Maximum Ratings ($T_A=25^\circ C$)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	
Continuous Drain Current @ $V_{GS}=10V, T_C=25^\circ C$ (silicon limit)	I_D	16	A
Continuous Drain Current @ $V_{GS}=10V, T_C=25^\circ C$ (package limit)		7	
Continuous Drain Current @ $V_{GS}=10V, T_C=100^\circ C$		7	
Continuous Drain Current @ $V_{GS}=10V, T_A=25^\circ C$		5.5	
Continuous Drain Current @ $V_{GS}=10V, T_A=70^\circ C$		4.4	
Pulsed Drain Current		I_{DM}	
Continuous Body Diode Forward Current @ $T_C=25^\circ C$	I_S	7	W
Pulsed Body Diode Forward Current @ $T_C=25^\circ C$	I_{SM}	28	
Total Power Dissipation	$T_C=25^\circ C$	18	
	$T_C=100^\circ C$	7.2	
	$T_A=25^\circ C$	2	
	$T_A=70^\circ C$	1.3	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-55~+150	$^\circ C$
Steady State Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	7	$^\circ C/W$
Steady State Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	63	



Electrical Characteristics (T_A=25°C, unless otherwise specified)

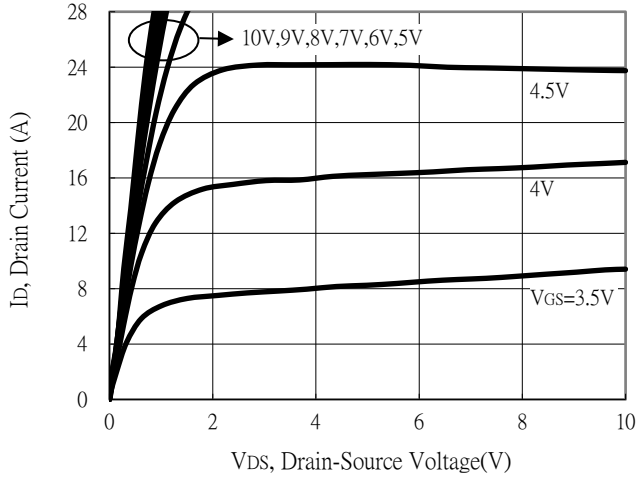
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Static					
BV _{DSS}	60	-	-	V	V _{GS} =0V, I _D =250μA
V _{GS(th)}	1	-	2.5		V _{DS} =V _{GS} , I _D =250μA
G _{FS}	-	4.6	-	S	V _{DS} =10V, I _D =4A
I _{GSS}	-	-	±10	μA	V _{GS} =±16V, V _{DS} =0V
I _{DSS}	-	-	1		V _{DS} =48V, V _{GS} =0V
R _{DS(ON)}	-	28	38	mΩ	V _{GS} =10V, I _D =4A
	-	40	56		V _{GS} =4.5V, I _D =3A
Dynamic					
C _{ISS}	-	483	-	pF	V _{DS} =30V, V _{GS} =0V, f=1MHz
C _{OSS}	-	75	-		
C _{ISS}	-	22	-		
R _g	-	9.5	-	Ω	f=1MHz
Q _g *d,e	-	4.5	-	nC	V _{DS} =30V, I _D =5A, V _{GS} =4.5V
Q _g *d,e	-	8.8	-		
Q _{gs} *d,e	-	1.9	-		
Q _{gd} *d,e	-	1.7	-		
t _{d(ON)} *d,e	-	6.2	-	ns	V _{DS} =30V, I _D =5A, V _{GS} =10V
tr *d,e	-	15	-		
t _{d(OFF)} *d,e	-	26	-		
t _f *d,e	-	6.4	-		
Source-Drain Diode					
V _{SD} *d	-	0.85	1.2	V	I _S =4A, V _{GS} =0V
t _{rr}	-	11	-	ns	I _F =5A, di/dt=100A/μs
Q _{rr}	-	4.8	-	nC	

Note:

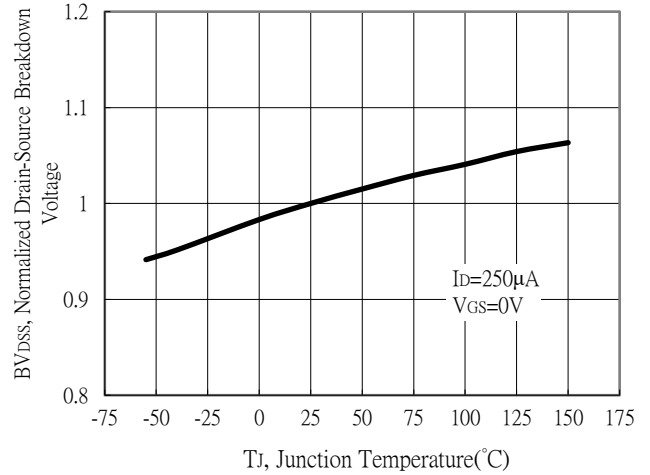
- *a. The power dissipation P_D is based on T_{J(MAX)}=150°C, using junction-to-case thermal resistance, and is more useful in setting the upper Dissipation.
- *b. The value of R_{θJA} is measured with the device mounted on 1in² FR-4 board with 2oz copper, in a still air environment with T_A=25°C. The power dissipation P_D is based on R_{θJA} and the maximum allowed junction temperature of 150°C. The value in any given application depends on the user's specific board design.
- *c. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)}=150°C. Ratings are based on low frequency and low duty cycles to keep initial T_J=25°C.
- *d. Pulse Test : Pulse Width≤300μs, Duty Cycle≤2%.
- *e. Independent of operating temperature.

Typical Characteristics

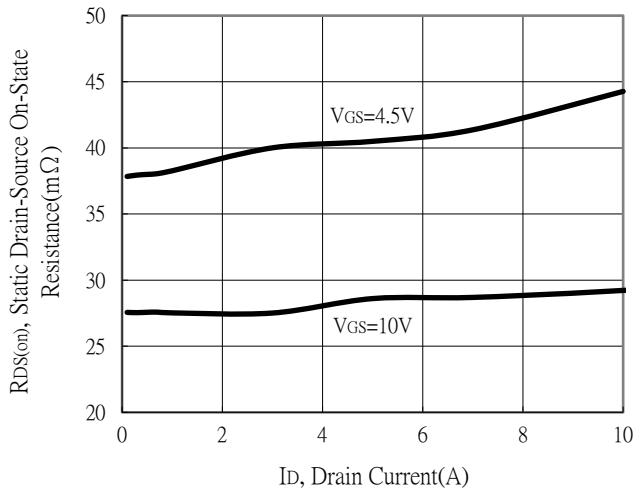
Typical Output Characteristics



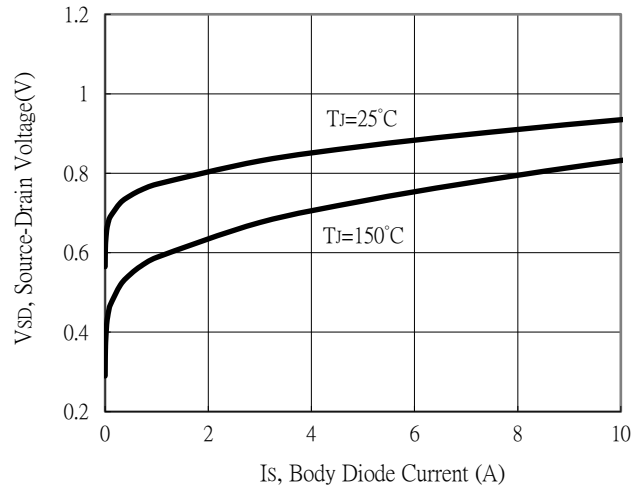
Breakdown Voltage vs Ambient Temperature



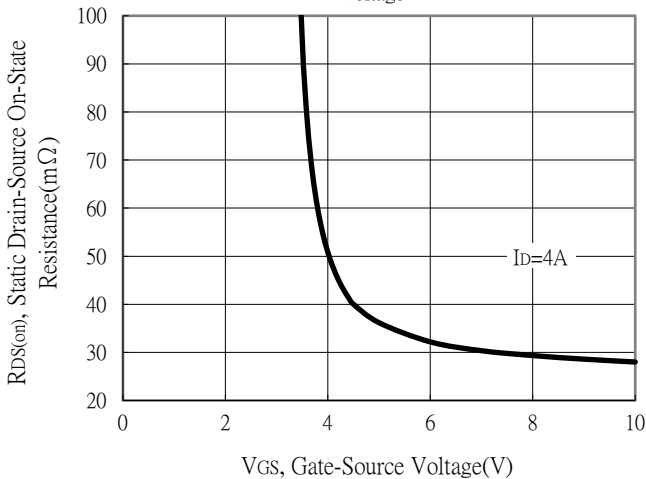
Static Drain-Source On-State resistance vs Drain Current



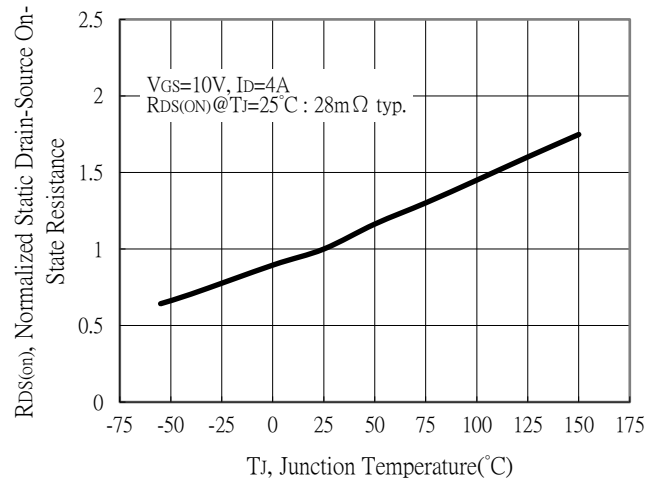
Body Diode Current vs Source-Drain Voltage



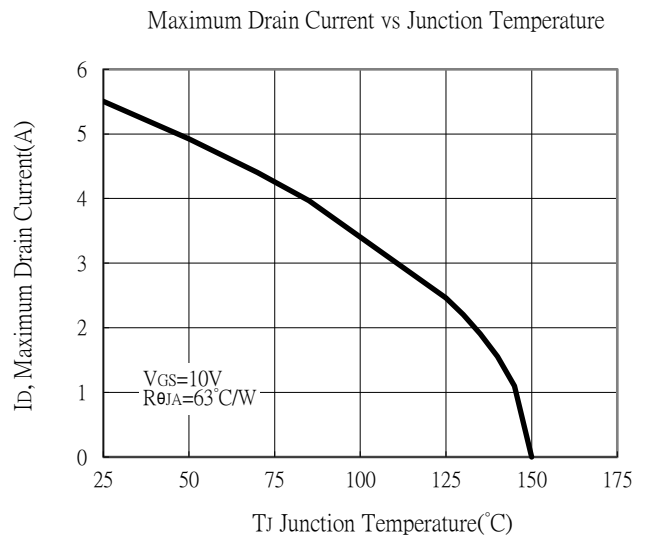
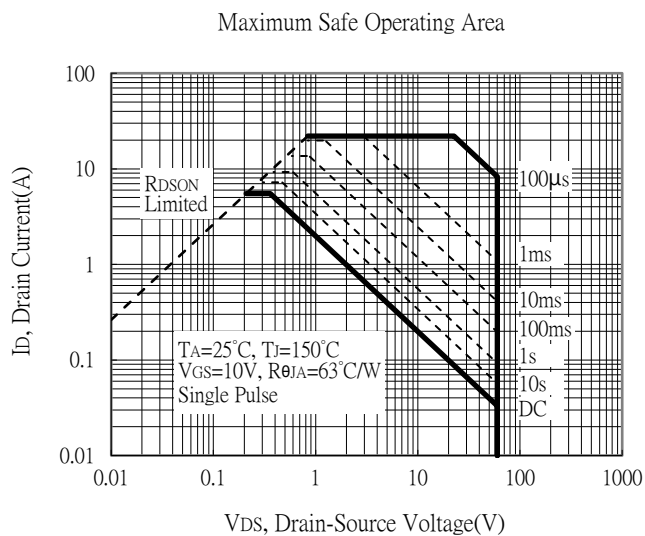
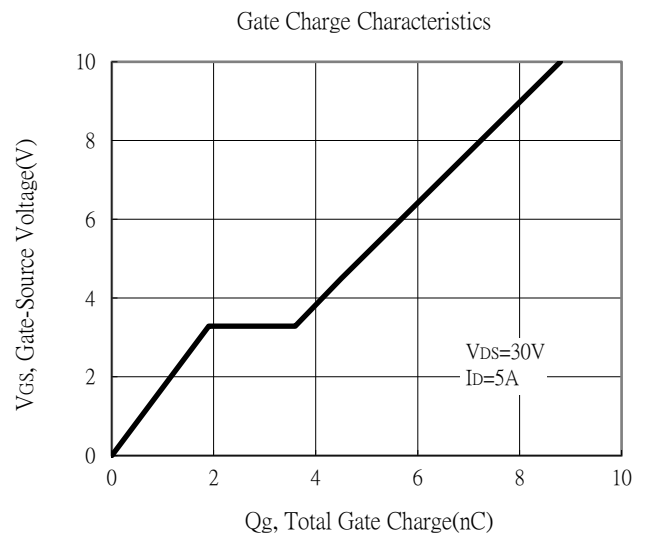
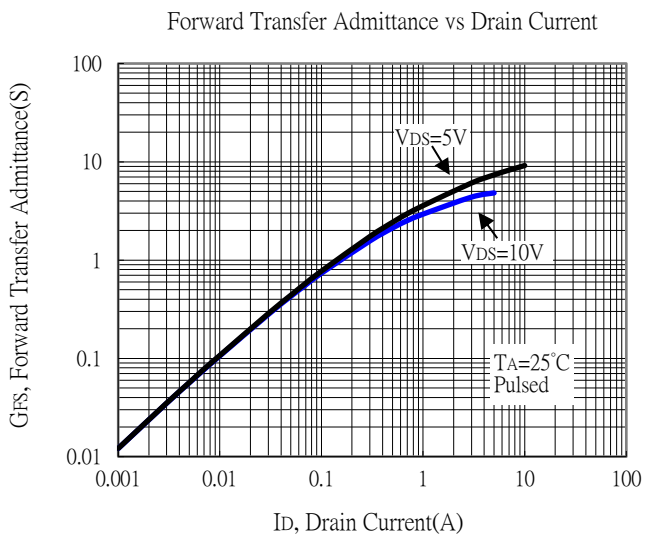
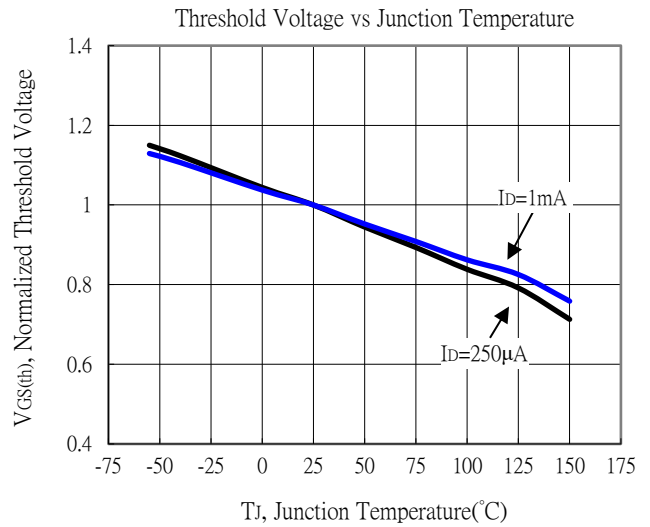
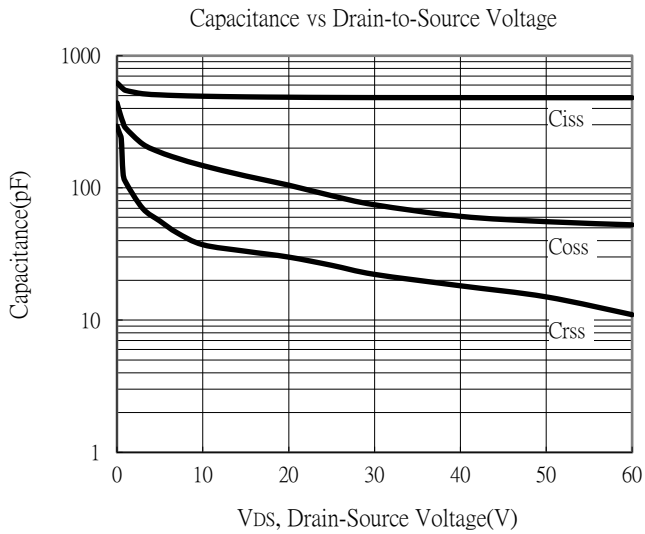
Static Drain-Source On-State Resistance vs Gate-Source Voltage



Drain-Source On-State Resistance vs Junction Temperature

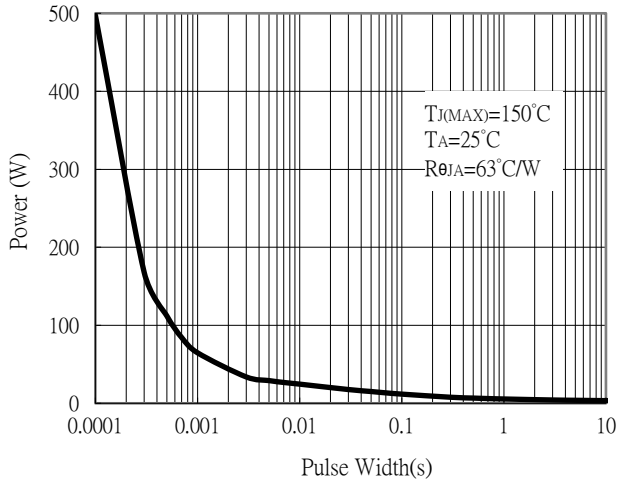


Typical Characteristics

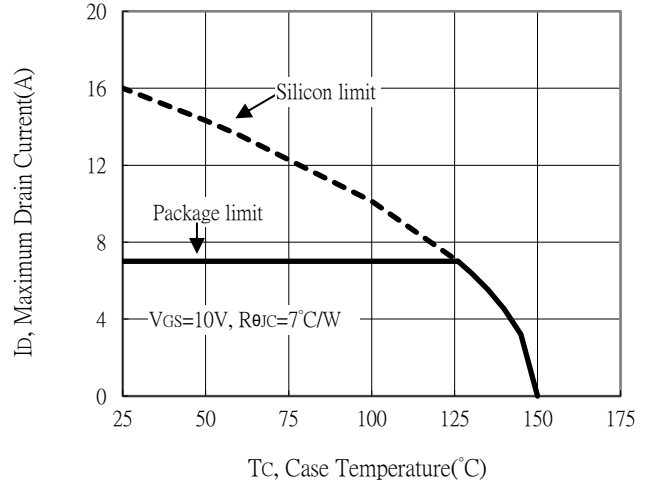


Typical Characteristics

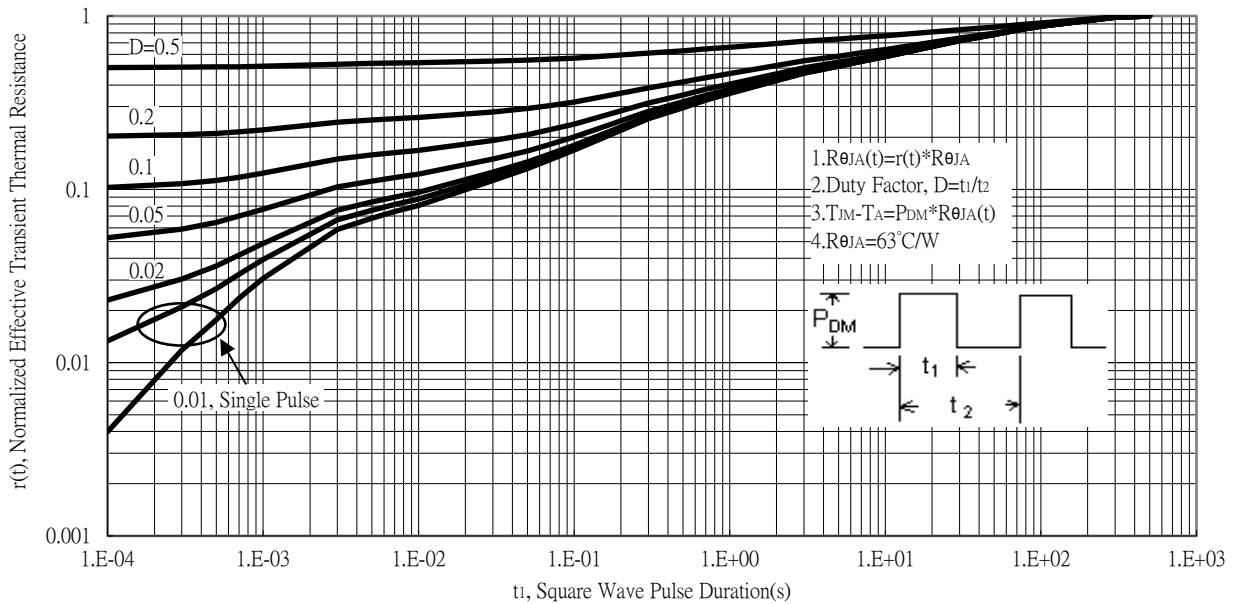
Single Pulse Power Rating, Junction to Ambient



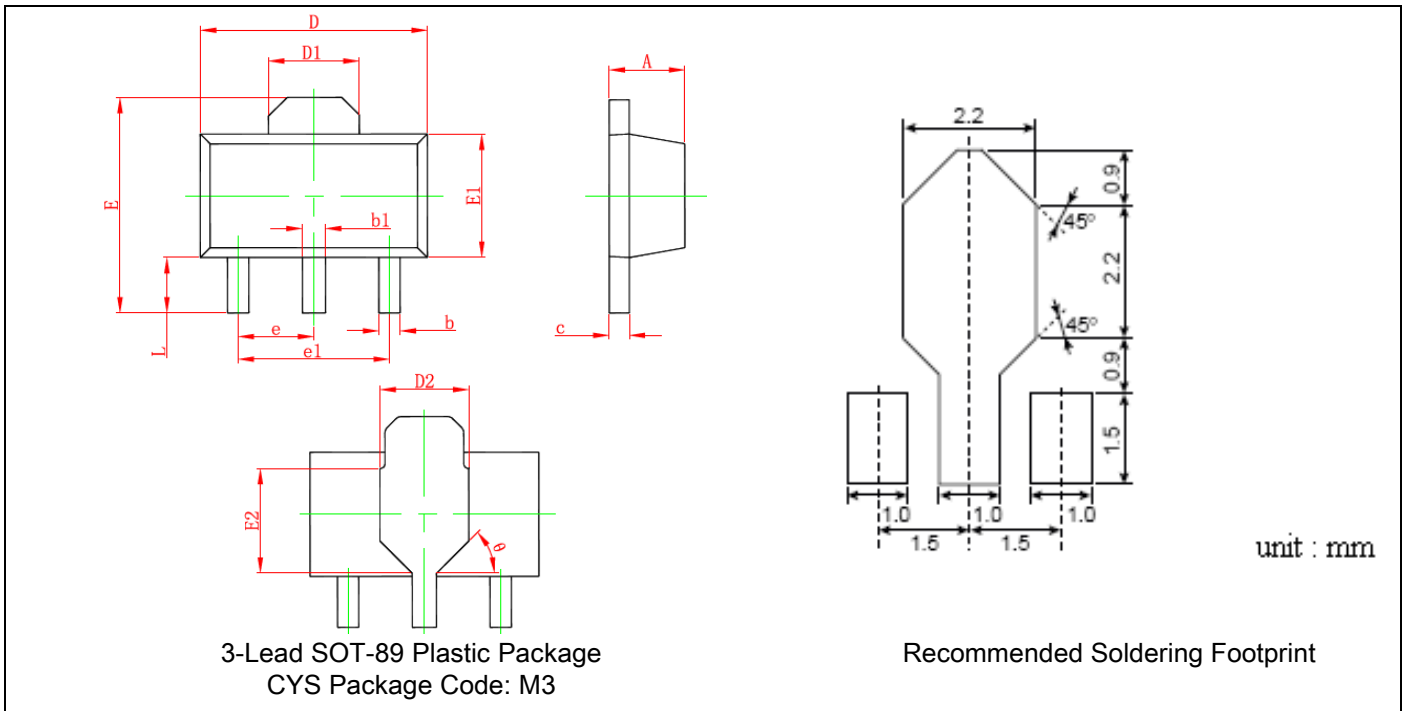
Maximum Drain Current vs Case Temperature



Transient Thermal Response Curves



SOT-89 Dimension



DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.055	0.063	1.40	1.60	E	0.155	0.167	3.94	4.25
b	0.013	0.020	0.32	0.52	E1	0.091	0.102	2.30	2.60
b1	0.016	0.023	0.40	0.58	E2	0.075	REF.	1.90	REF.
c	0.014	0.017	0.35	0.44	e	0.060	TYP.	1.50	TYP.
D	0.173	0.181	4.40	4.60	e1	0.118	TYP.	3.00	TYP.
D1	0.061	REF.	1.55	REF.	L	0.035	0.047	0.90	1.20
D2	0.069	REF.	1.75	REF.	θ	45°		45°	

Note:

- Controlling dimension: millimeters.
- Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
- If there is any question with packing specification or packing method, please contact your local CYStek sales office.

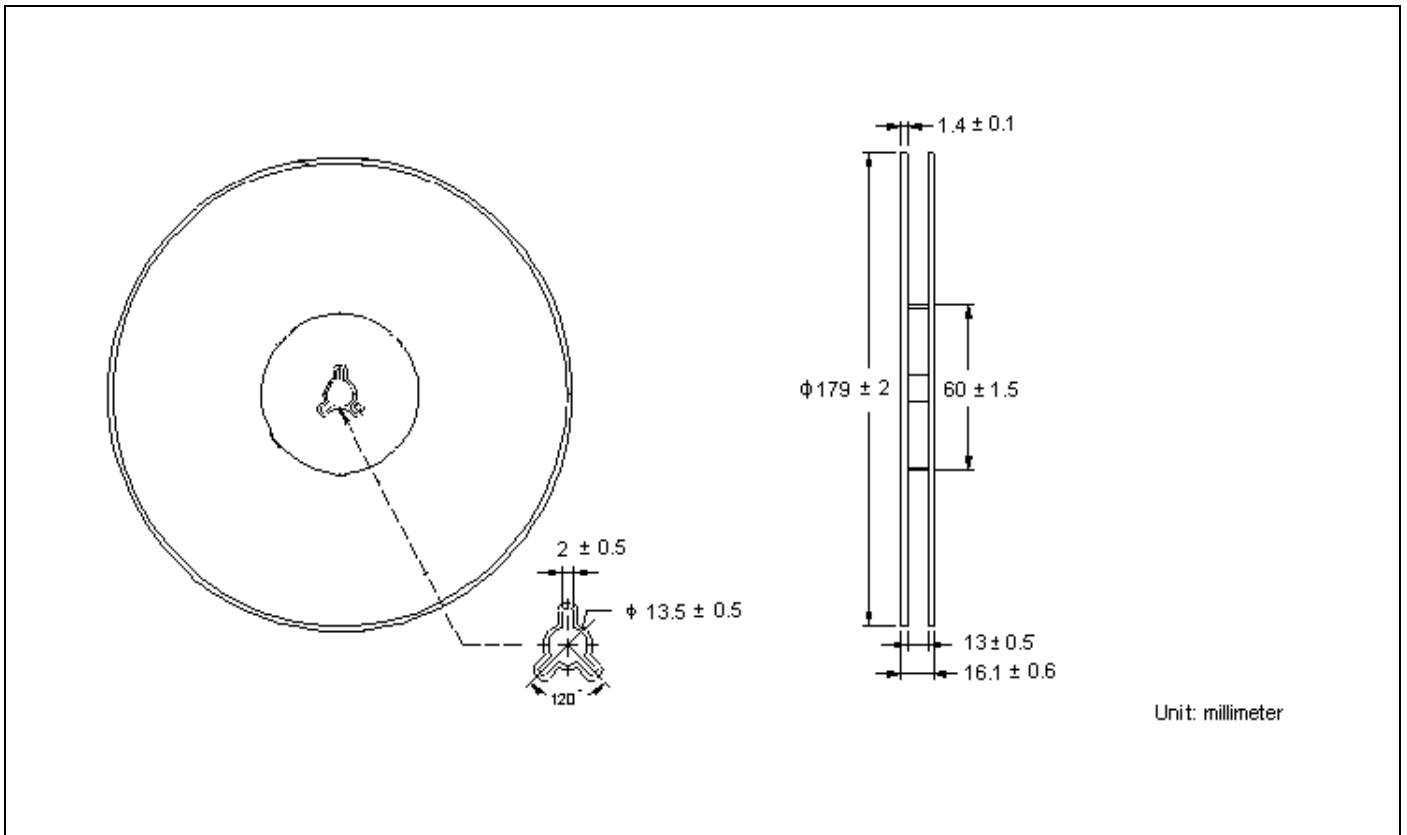
Material:

- Lead: pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

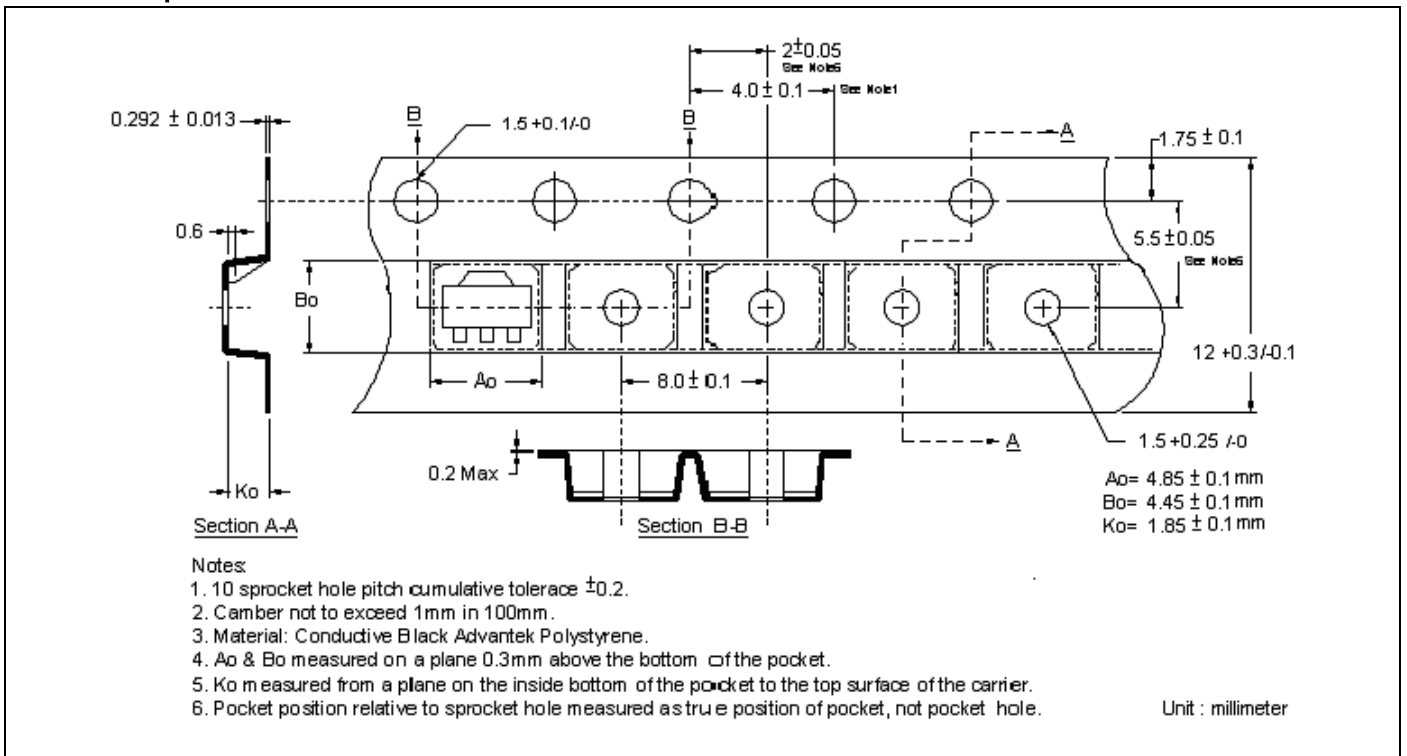
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Reel Dimension



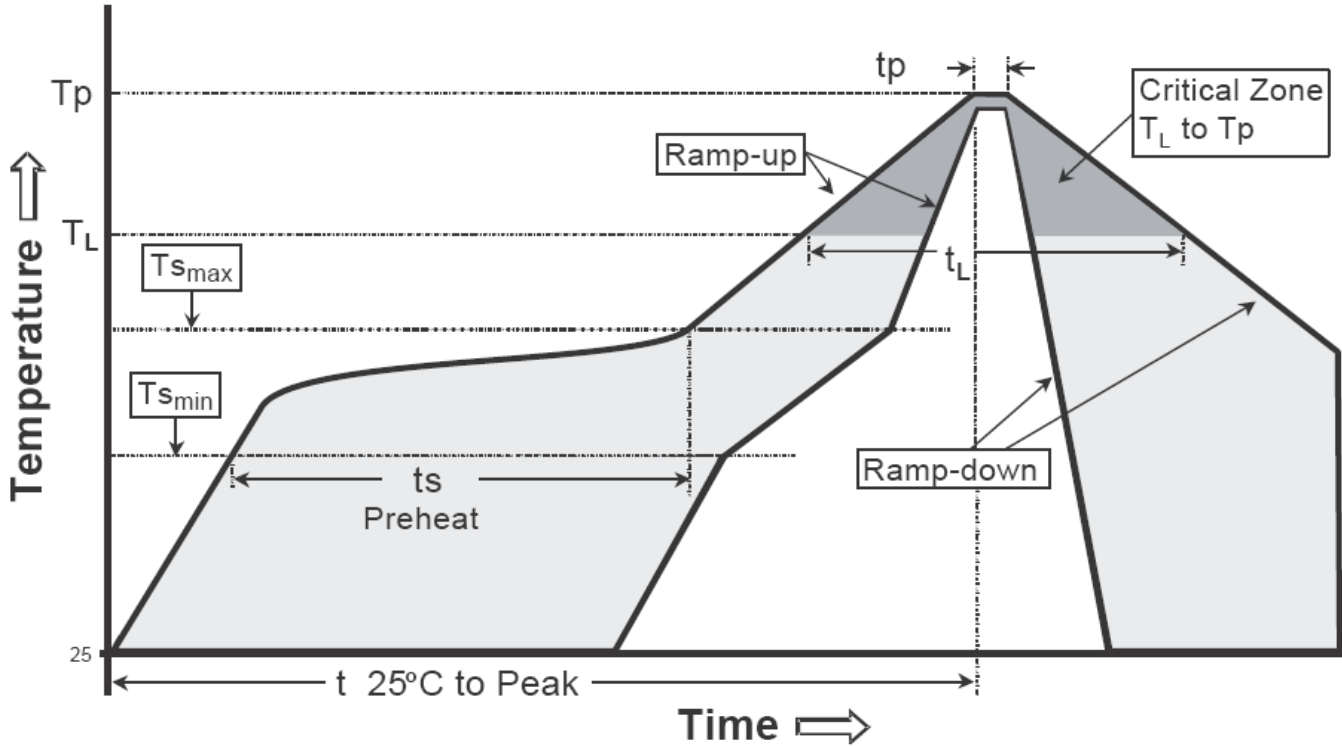
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

Recommended temperature profile for IR reflow



Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _S max to T _P)	3°C/second max.	3°C/second max.
Preheat -Temperature Min (T _S min) -Temperature Max (T _S max) -Time (t _s min to t _s max)	100°C 150°C 60-120 seconds	150°C 200°C 60-180 seconds
Time maintained above: -Temperature (T _L) -Time (t _L)	183°C 60-150 seconds	217°C 60-150 seconds
Peak Temperature (T _P)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature (t _P)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note:

- All temperatures refer to topside of the package, measured on the package body surface.